MA2SD190G

Silicon epitaxial planar type

For super high speed switching

■ Features

• Forward current (Average) $I_{F(AV)} = 200 \text{ mA}$ rectification is possible

• Low forward voltage: $V_F < 0.47 \text{ V}$

• Small reverse current: $I_R < 15 \mu A$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	20	V
Repetitive peak reverse voltage	V_{RRM}	20	V
Forward current (Average)	I _{F(AV)}	200	mA
Peak forward current	I _{FM}	300	mA
Non-repetitive peak forward	I _{FSM}	1	A
surge current *			
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Package

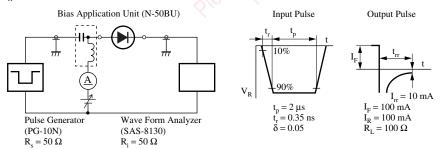
- Code
 - SSMini2-F4
- Pin Name
 - 1: Anode
- 2: Cathode

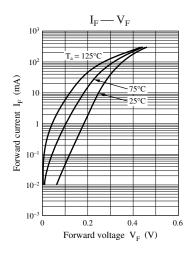
Marking Symbol: 3L

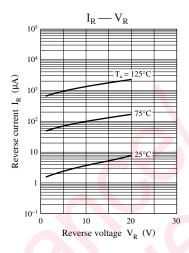
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

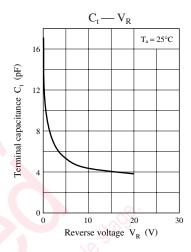
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 200 \text{ mA}$	100	0,	0.47	V
Reverse current	I_R	$V_R = 10 \text{ V}$		O -	15	μΑ
Terminal capacitance	C_t	$V_R = 0 V, f = 1 MHz$	9.0	15		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

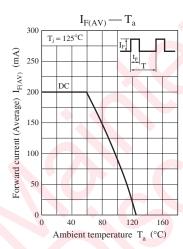
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz.
 - 4. *: t_{rr} measurement circuit





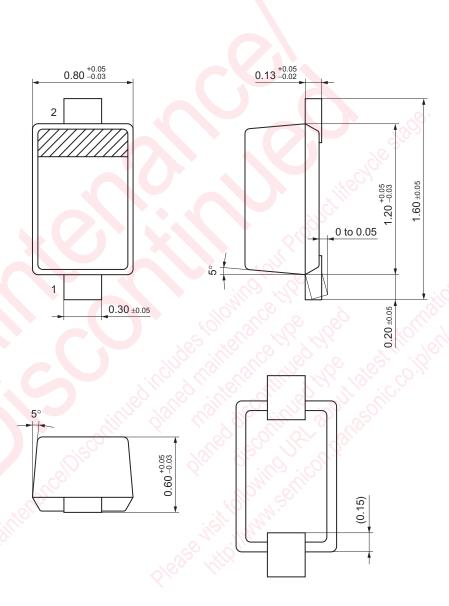






2 SKH00177AED

SSMini2-F4 Unit: mm



SKH00177AED 3

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